

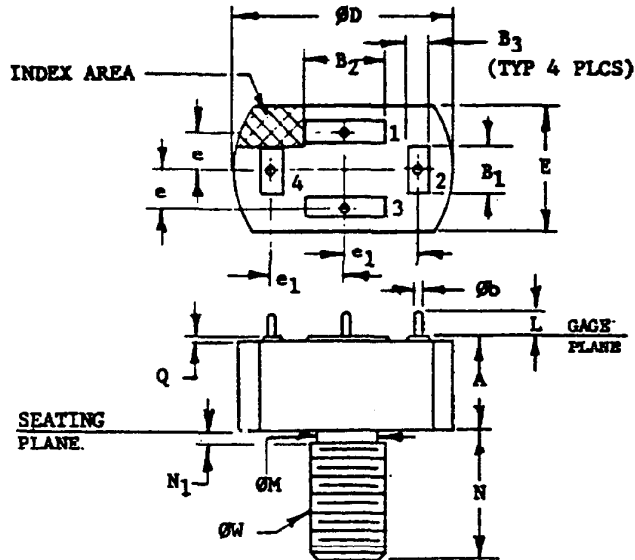
# NOTES:

1. Refer to rules for dimensioning semiconductor product outlines
2.  $\phi W$  is pitch diameter of coated threads. Ref.: Unified Screw Threads, ANS B1.1-1960.
3. Lead spacing to be measured at the Gage Plane.

SYMBOL	VARIATIONS (ALL DIMENSIONS SHOWN IN MILLIMETERS)										
	AA		NOTE			NOTE			NOTE		
	MIN.	MAX.		MIN.	MAX.		MIN.	MAX.		MIN.	MAX.
A	7.50	8.25									
$B_1$	3.43	3.81									
$B_2$	5.97	6.35									
$B_3$	1.397	1.651									
$\phi b$	.508	.635									
$\phi D$	16.51	17.27									
E	9.15	9.65									
e	2.82	3.32	3								
$e_1$	5.42	5.91	3								
L	1.76	2.23									
$\phi M$	5.59	6.32									
N	10.67	11.68									
$N_1$	—	2.28									
Q	.00	.038									
$\phi W$	1/4-28 UNF 2A		2								
NOTE	1										
REF.	Item 279G										
ISSUE	A May, 1971										
JEDEC SEMICONDUCTOR DEVICE OUTLINES				TITLE STUD RECTANGULAR BASE FAMILY			ISSUE A		DATE MAY 1971		T0-217AA

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SYMBOL	VARIATIONS (ALL DIMENSIONS SHOWN IN INCHES)												
	AA		NOTE			NOTE			NOTE			NOTE	
	MIN.	MAX.		MIN.	MAX.		MIN.	MAX.		MIN.	MAX.		
A	.295	.325											
B <sub>1</sub>	.135	.150											
B <sub>2</sub>	.235	.250											
B <sub>3</sub>	.055	.065											
Øb	.020	.025											
ØD	.650	.680											
E	.360	.380											
e	.111	.131	3										
e <sub>1</sub>	.213	.233	3										
L	.069	.088											
ØM	.220	.249											
N	.420	.460											
N <sub>1</sub>	—	.090											
Q	.000	.015											
ØW	1/4-28 UNF 2A		2										
NOTE	1												
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